

ESCC (a) 4001/023 Qualified R Failure Rate High Precision (10 ppm/°C, 0.05 %) Thin Film Chip Resistors



Vishay Sfernice Thin Film division holds ESCC QML qualification (ESCC technology flow qualification).

These HiRel components are ideal for low noise and precision applications, superior stability, low temperature coefficient of resistance, and low voltage coefficient, Vishay Sfernice's precision thin film wraparound resistors exceed requirements of MIL-PRF-55342G characteristics Y (± 10 ppm/°C).

FEATURES

HALOGEN FREE

- Load life stability at ± 70 °C for 2000 h: 0.25 % under Pn
- Temperature coefficient to: 10 ppm/°C
- Very low noise (< -35 dB) and voltage coefficient (< 0.01 ppm/V)
- Resistance range: 100 Ω to 3.01 M Ω (depending on size)
- Tolerances down to 0.05 %
- SnPb terminations over nickel barrier
- ESCC 4001 (generic specification)
- ESCC 4001/023 (detail specification)
- ESCC qualified
- R failure rate (0.01 % per 1000 h)
- SMD wraparound chip resistor
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

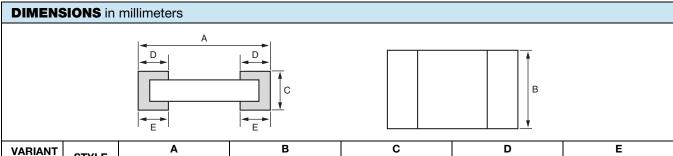
STANDARD ELECTRICAL SPECIFICATIONS										
MODEL	SIZE	ESCC VARIANT NUMBER	RESISTANCE RANGE Ω	RATED POWER AT + 70 °C (Pn) W	LIMITING ELEMENT VOLTAGE (UL) V	INSULATION VOLTAGE (U _i) V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C		
PFRR 0402 📀	0402	15	100 to 150K	0.05	30	40	0.05, 0.1	10, 25		
PFRR 0603 💿	0603	09	100 to 500K	0.1	50	100	0.05, 0.1	10, 25		
PFRR 0805 📀	0805	10	100 to 750K	0.125	100	200	0.05, 0.1	10, 25		
PFRR 1206 🕝	1206	11	100 to 3.5M	0.25	150	300	0.05, 0.1	10, 25		
PFRR 2010 @	2010	12	100 to 6M	0.50	200	300	0.05, 0.1	10, 25		

CLIMATIC SPECIFICATIONS						
Operating temperature range	-55 °C; +155 °C					
Soldering temperature (T _{sol})	260 °C, immersion 10 s					

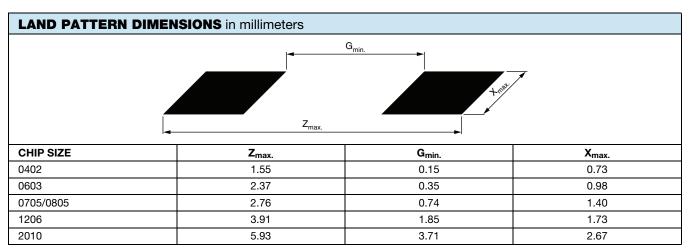
MECHANICAL SPECIFICATIONS						
Substrate material	Alumina					
Technology	Thin Film					
Film	Nickel Chromium with mineral passivation					
Protection	Epoxy and Silicon					
Terminations	B type: SnPb over nickel barrier for solder reflow					

QUALIFIED OHMIC RANGE: MAX. VALUE								
PFRR0402	PFRR0402 PFRR0603 PFRR0805 PFRR1206 PFRR2010							
100 kΩ	261 kΩ	301 kΩ	1 ΜΩ	3.01 MΩ				





VARIANT NUMBER	STYLE	Į.	4		3	())	E	.
		Min.	Max.								
09	0603	1.39	2.16	0.62	1.01	0.25	1.02	0.17	0.51	0.25	0.51
10	0805	1.78	2.55	1.14	1.53	0.25	1.02	0.17	0.51	0.25	0.51
11	1206	2.87	3.64	1.47	1.86	0.25	1.02	0.17	0.51	0.25	0.51
12	2010	4.95	5.72	2.41	2.8	0.25	1.02	0.35	0.85	0.35	0.85
15	0402	0.87	1.64	0.47	0.86	0.25	1.02	0.09	0.38	0.12	0.38



Note

Suggested land pattern: According to IPC-7351

TRACEABILITY DEFINITIONS

The two major traceability elements are defined as:

- The primary process lot number named Front End lot (FE lot). One "FE lot" is composed of several wafers issued from the same thin film deposition sequence.
- The date code named Batch Number(BN). The "BN" is defined after completion of the end of production testing sequence. The lot homogeneity is given by the "FE lot" and not by the "BN".

According to the applied rules validated by the ESCC through the product qualification, the following situations are agreed:

- Parts coming from different "FE lost" might have the same "BN".
- A maximum of two different "BN" might be applied to the same "FE lot" to enable the use of overruns from a previous PO.
- Unless requested / approved by the customer the "BN" will be 2 years old maximum.

SPECIFIC TRACEABILITY REQUIREMENTS

The following specific requirements have to be treated as:

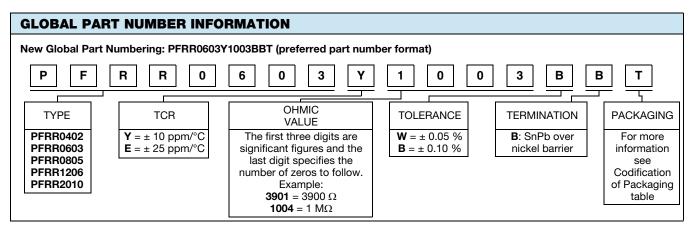
- A customer who requires "Lot Homogeneity" has to mention it on the PO as "SINGLE PRODUCTION LOT".
- A customer who requires "Lot Homogeneity" in addition to a "Single Batch Number" has to mention it on the PO as "SINGLE PRODUCTION LOT AND OPTION R0101".

END OF PRODUCTION TESTING

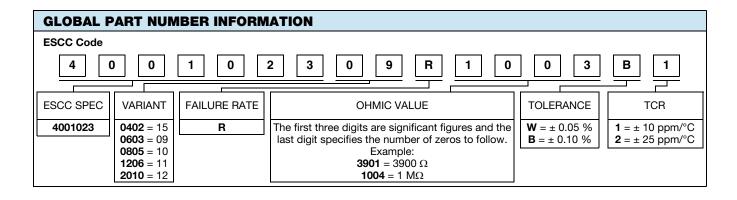
Mandatory testing performed at the end of the production process:

• 100 % overload: Voltage $\sqrt{(6.25 P_p \times R_p)}$ or 2 U_L whichever is less - duration 2 s





CODIFICATION OF PACKAGING							
CODE 18	PACKAGING						
WAFFLE PACK							
W	100 min., 1 mult						
WA	100 min., 100 mult (available only in size 1206)						
PLASTIC TAPE (in standard for a	all sizes except 0402)						
Т	100 min., 1 mult						
TA	100 min., 100 mult						
ТВ	250 min., 250 mult						
TC	500 min., 500 mult						
TD	1000 min., 1000 mult						
TE	2500min., 2500 mult						
TF	Full tape (quantity depending on size of chips)						
PAPER TAPE (in standard for 04	02, option for other sizes)						
PT	100 min., 1 mult						
PA	100 min., 100 mult						
РВ	250 min., 250 mult						
PC	500 min., 500 mult						
PD	1000 min., 1000 mult						
PE	2500min., 2500 mult						
PF	Full tape (quantity depending on size of chips)						



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Vishay Sfernice thin film is the first passive manufacturer to hold the ESCC Technology Flow Qualification, official certificate is available on ESCIES web site https://escies.org/ReadArticle?docId=727).

This qualification open the door to a new concept at ESA: The Failure Rate option (similar to the one offered in the MIL system), for instance R failure rate: 0.01 % per 1000 h.

New specifications describing this new concept have been released by the ESA:

2544001: Requirements for the Technology Flow Qualification of Film Resistors

https://escies.org/escc/specifications/2544001.pdf

26000: Failure Rate Level Sampling Plans and Procedures https://escies.org/escc/specifications/26000.pdf

21300: Terms, Definitions, Abbreviations, Symbols and Units https://escies.org/escc/specifications/21300.pdf

21700: General Requirements for the Marking of the ESCC Components

https://escies.org/escc/specifications/21700.pdf

4001: Generic Specification Resistors Fixed Film https://escies.org/escc/specifications/4001.pdf

4001023: Resistors, Fixed, Chip, Thin Film, Type PHR and PFRR

https://escies.org/escc/specifications/4001023.pdf

Parts are delivered with space C.O.C.

Parts undergo 100 % overload at end of production process.

ESCC/PFRR CODIFICATION CORRESPONDANCE TABLES

VARIANT	MODEL	CASE SIZE	TERMINATION
15	PFRR	0402	B (tin/lead)
09	PFRR	0603	B (tin/lead)
10	PFRR	0805	B (tin/lead)
11	PFRR	1206	B (tin/lead)
12	PFRR	1210	B (tin/lead)

Ī	TEMPERATURE COEFFICIENT	ESCC CODE	PFRR CODE
Ī	10 ppm/°C (- 55 °C; + 155 °C)	1	Υ
Ī	25 ppm/°C (- 55 °C; + 155 °C)	2	E

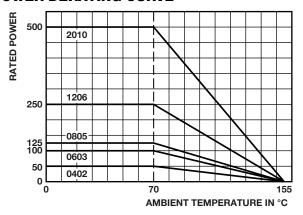
TOLERANCE	MODEL	CASE SIZE	
0.1 %	В	В	
0.05 %	W	W	

PACKAGING

Two types of packaging are available: waffle-pack and tape and reel.

and reel.								
	NUMBER O	NUMBER OF PIECES PER PACKAGE						
SIZE	WAFFLE	TAPE AN	TAPE					
	PACK 2" × 2"	MIN.	MAX.	WIDTH				
0402	340		5000					
0603	100		3000					
0805	100	100	4000	8 mm				
1206	140		4000					
2010	60		2000					

POWER DERATING CURVE



EXTENDED FEATURES

You may consult Vishay Sfernice for chip sizes, ohmic values and tolerances outside of the qualified range.



PERFORMANCE							
TEST	CONDITIONS	REQUIREMEN	TYPICAL				
1531	CONDITIONS	ESA/SCC 4001/023	MIL-PRF-55342G	ITPIOAL			
Short time overload	$U = \sqrt{(6.25 \text{ Pr x Rn})}$ $U_{\text{max.}} < 2 \text{ UL} - 2 \text{ s}$	± 0.05 % + (0.05 Ω x 100/Rn)	0.10 %	± 0.01 %			
Rapid temperature change	- 55 °C/+ 155 °C 5 cycles CEI 66-2-14 Test Na	± 0.05 % + (0.05 Ω x 100/Rn)	0.1 % (for 100 cycles)	± 0.01 % ± 0.015 % (for 500 cycles)			
Soldering (thermal shock)	260 °C/10 s CEI 68-2-20 A Test T6 (met. 1A)	± 0.05 % + (0.05 Ω x 100/Rn)	-	± 0.005 %			
Terminal strength: Adhesion bend strength of end plated facing	CEI 115-1 Clause 4.32 CEI 115-1 Clause 4.33	± 0.05 % + (0.05 Ω x 100/Rn)	-	± 0.01 %			
Climatic sequence	CEI 67-2-1/CEI 68-2-2 CEI 67-2-13/CEI 68-2-30	± 0.10 % + (0.05 Ω x 100/Rn)	-	$\pm~0.02~\%$ Insulation resistance > 1 $G\Omega$			
Load life	2000 h Pr at + 70 °C 90'/30' cycle 8000 h	± 0.25 % + (0.05 Ω x 100/Rn) 1 % + (0.05 Ω x 100/Rn)	0.5 %	\pm 0.05 % (8000 h) Insulation resistance > 1 $G\Omega$			
High temperature exposure	2000 h Pr at + 155 °C CEI 68-2-20A Test B	± 0.15 % + (0.05 Ω x 100/Rn)	± 0.10 % (duration 1000 h)	$\pm~0.05~\%$ Insulation resistance > 1 $G\Omega$			



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